



Technical Bulletin

- Place a copy of this bulletin in the front of each Blueprints Manual.
- Redline drawings as needed and include a TB reference note.
- Document TB implementation schedule request and completion:

TB Number: 098
Date Issued: Nov10, 2014
Expiration Date: none

Date Scheduled _____ Date Completed _____
 Completed by (name) _____

Subject/Key Words:	CIP, Advanced Phos Control (APC): Avoid DIW dehydration and wafer cross slotting			
Classification:	<input checked="" type="checkbox"/> Informational	<input type="checkbox"/> Mandatory	<input type="checkbox"/> Safety Alert	<input type="checkbox"/> Preventive Maintenance Impact
	<input type="checkbox"/> Warranty Impact	<input type="checkbox"/> Purchase Parts	<input type="checkbox"/> No Charge For Parts expires ___ / ___ / ___. Reference this TB# when ordering NC parts.	
Application:	Gama PRM modules having APC DIW Concentration Control			
Parts/Documents:	Applicable hardware kits: 239925-001, 239924-001, or 240124-001 plus APC feature specific software.			
Attachments:	none			

Issue: Continual Improvement Process initiatives have been driven to optimize the APC DIW concentration feature issued on new tool and product enhancement purchases.

Nitride Etch processes control algorithm has been analyzed to understand DIW dehydration phenomena and associated bath turbulence which is attributed to periodic wafer cross slotting.

Inspection: Systems affected by project number: 0334-01*, 0343-01, 0343-06, 1101-01, 1205-03*, 1309-01, 1334-01, 1593-01, 1609-02* (* solution implemented and validated)

Solution: APC software enhancements: to activate DIW spiking during mix time to avoid dehydration of the phosphoric bath and to disable DIW spiking during conditions which will lead to over hydration.

A hardware kit will also be issued and installed to ensure position of the ASG sensor tube for stable readings.

Akrion Systems field service managers will contact affected customers to make arrangements for installation of these CIP upgrades.